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(54) Title: UNSUPERVISED PATTERN SYNONYM DETECTION USING IMAGE HASHING

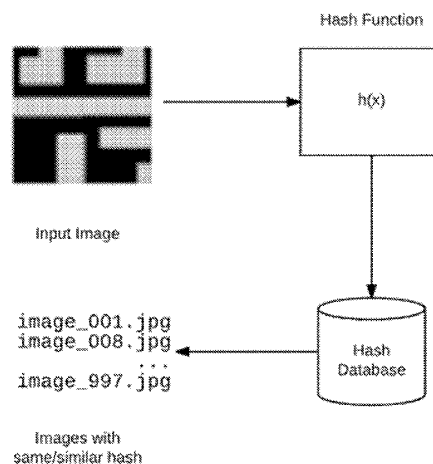


FIG. 2

(57) Abstract: Images of semiconductor wafers can be hashed to determine a fixed length hash string for each of the images. Pattern synonyms can be determined from the hash strings. The pattern synonyms can be grouped. A degree of similarity between images in the groups is adjustable via a hamming distance. This can be used for various applications, including determination of latent defects.

[Continued on next page]

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